

NGB8204N, NGB8204AN

UNCLAMPED COLLECTOR-TO-EMITTER AVALANCHE CHARACTERISTICS ($-55^{\circ} \leq T_J \leq 175^{\circ}C$)

Characteristic	Symbol	Value	Unit
Single Pulse Collector-to-Emitter Avalanche Energy $V_{CC} = 50\text{ V}$, $V_{GE} = 5.0\text{ V}$, Pk $I_L = 21.1\text{ A}$, $L = 1.8\text{ mH}$, Starting $T_J = 25^{\circ}C$ $V_{CC} = 50\text{ V}$, $V_{GE} = 5.0\text{ V}$, Pk $I_L = 18.3\text{ A}$, $L = 1.8\text{ mH}$, Starting $T_J = 125^{\circ}C$	E_{AS}	400 300	mJ
Reverse Avalanche Energy $V_{CC} = 100\text{ V}$, $V_{GE} = 20\text{ V}$, Pk $I_L = 25.8\text{ A}$, $L = 6.0\text{ mH}$, Starting $T_J = 25^{\circ}C$	$E_{AS(R)}$	2000	mJ

MAXIMUM SHORT-CIRCUIT TIMES ($-55^{\circ}C \leq T_J \leq 150^{\circ}C$)

Short Circuit Withstand Time 1 (See Figure 17, 3 Pulses with 10 ms Period)	t_{sc1}	750	μs
Short Circuit Withstand Time 2 (See Figure 18, 3 Pulses with 10 ms Period)	t_{sc2}	5.0	ms

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.3	$^{\circ}C/W$
Thermal Resistance, Junction-to-Ambient D ² PAK (Note 1)	$R_{\theta JA}$	50	$^{\circ}C/W$
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds (Note 2)	T_L	275	$^{\circ}C$

- When surface mounted to an FR4 board using the minimum recommended pad size.
- For further details, see Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Test Conditions	Temperature	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector-Emitter Clamp Voltage	BV_{CES}	$I_C = 2.0\text{ mA}$	$T_J = -40^{\circ}C$ to $150^{\circ}C$	380	395	420	V_{DC}
		$I_C = 10\text{ mA}$	$T_J = -40^{\circ}C$ to $150^{\circ}C$	390	405	430	
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE} = 350\text{ V}$, $V_{GE} = 0\text{ V}$	$T_J = 25^{\circ}C$	-	2.0	10	μA_{DC}
			$T_J = 150^{\circ}C$	-	10	40*	
			$T_J = -40^{\circ}C$	-	1.0	10	
Reverse Collector-Emitter Leakage Current	I_{ECS}	$V_{CE} = -24\text{ V}$	$T_J = 25^{\circ}C$	-	0.7	1.0	mA
			$T_J = 150^{\circ}C$	-	12	25*	
			$T_J = -40^{\circ}C$	-	0.1	1.0	
Reverse Collector-Emitter Clamp Voltage	$BV_{CES(R)}$	$I_C = -75\text{ mA}$	$T_J = 25^{\circ}C$	27	33	37	V_{DC}
			$T_J = 150^{\circ}C$	30	36	40	
			$T_J = -40^{\circ}C$	25	32	35	
Gate-Emitter Clamp Voltage	BV_{GES}	$I_G = 5.0\text{ mA}$	$T_J = -40^{\circ}C$ to $150^{\circ}C$	11	13	15	V_{DC}
Gate-Emitter Leakage Current	I_{GES}	$V_{GE} = 10\text{ V}$	$T_J = -40^{\circ}C$ to $150^{\circ}C$	384	640	700	μA_{DC}
Gate Emitter Resistor	R_{GE}	-	$T_J = -40^{\circ}C$ to $150^{\circ}C$	10	16	26	$k\Omega$

ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	$V_{GE(th)}$	$I_C = 1.0\text{ mA}$, $V_{GE} = V_{CE}$	$T_J = 25^{\circ}C$	1.1	1.4	1.9	V_{DC}
			$T_J = 150^{\circ}C$	0.75	1.0	1.4	
			$T_J = -40^{\circ}C$	1.2	1.6	2.1*	
Threshold Temperature Coefficient (Negative)	-	-	-	-	3.4	-	$mV/^{\circ}C$

*Maximum Value of Characteristic across Temperature Range.

- Pulse Test: Pulse Width $\leq 300\ \mu s$, Duty Cycle $\leq 2\%$.

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ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Test Conditions	Temperature	Min	Typ	Max	Unit
ON CHARACTERISTICS (Note 3)							
Collector-to-Emitter On-Voltage	$V_{CE(on)}$	$I_C = 6.0 \text{ A},$ $V_{GE} = 4.0 \text{ V}$	$T_J = 25^\circ\text{C}$	1.0	1.4	1.6	V_{DC}
			$T_J = 150^\circ\text{C}$	0.9	1.3	1.6	
			$T_J = -40^\circ\text{C}$	1.1	1.45	1.7*	
		$I_C = 8.0 \text{ A},$ $V_{GE} = 4.0 \text{ V}$	$T_J = 25^\circ\text{C}$	1.3	1.6	1.9*	
			$T_J = 150^\circ\text{C}$	1.2	1.55	1.8	
			$T_J = -40^\circ\text{C}$	1.4	1.6	1.9*	
		$I_C = 10 \text{ A},$ $V_{GE} = 4.0 \text{ V}$	$T_J = 25^\circ\text{C}$	1.4	1.8	2.0	
			$T_J = 150^\circ\text{C}$	1.5	1.8	2.0	
			$T_J = -40^\circ\text{C}$	1.4	1.8	2.1*	
		$I_C = 15 \text{ A},$ $V_{GE} = 4.0 \text{ V}$	$T_J = 25^\circ\text{C}$	1.8	2.2	2.5	
			$T_J = 150^\circ\text{C}$	2.0	2.4	2.6*	
			$T_J = -40^\circ\text{C}$	1.7	2.1	2.5	
$I_C = 10 \text{ A},$ $V_{GE} = 4.5 \text{ V}$	$T_J = 25^\circ\text{C}$	1.3	1.8	2.0*			
	$T_J = 150^\circ\text{C}$	1.3	1.75	2.0*			
	$T_J = -40^\circ\text{C}$	1.4	1.8	2.0*			
Forward Transconductance	gfs	$V_{CE} = 5.0 \text{ V},$ $I_C = 6.0 \text{ A}$	$T_J = -40^\circ\text{C to } 150^\circ\text{C}$	8.0	14	25	Mhos

DYNAMIC CHARACTERISTICS

Input Capacitance	C_{ISS}	$V_{CC} = 25 \text{ V}, V_{GE} = 0 \text{ V}$ $f = 1.0 \text{ MHz}$	$T_J = -40^\circ\text{C to } 150^\circ\text{C}$	400	800	1000	pF
Output Capacitance	C_{OSS}			50	75	100	
Transfer Capacitance	C_{RSS}			4.0	7.0	10	

SWITCHING CHARACTERISTICS

Turn-Off Delay Time (Resistive)	$t_{d(off)}$	$V_{CC} = 300 \text{ V}, I_C = 6.5 \text{ A}$ $R_G = 1.0 \text{ k}\Omega, R_L = 46 \Omega,$	$T_J = 25^\circ\text{C}$	-	4.0	10	μSec
Fall Time (Resistive)	t_f	$V_{CC} = 300 \text{ V}, I_C = 6.5 \text{ A}$ $R_G = 1.0 \text{ k}\Omega, R_L = 46 \Omega,$	$T_J = 25^\circ\text{C}$	-	9.0	15	
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 10 \text{ V}, I_C = 6.5 \text{ A}$ $R_G = 1.0 \text{ k}\Omega,$ $R_L = 1.5 \Omega$	$T_J = 25^\circ\text{C}$	-	0.7	4.0	μSec
Rise Time	t_r	$V_{CC} = 10 \text{ V}, I_C = 6.5 \text{ A}$ $R_G = 1.0 \text{ k}\Omega,$ $R_L = 1.5 \Omega$	$T_J = 25^\circ\text{C}$	-	4.5	7.0	

*Maximum Value of Characteristic across Temperature Range.

3. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.

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TYPICAL ELECTRICAL CHARACTERISTICS (unless otherwise noted)

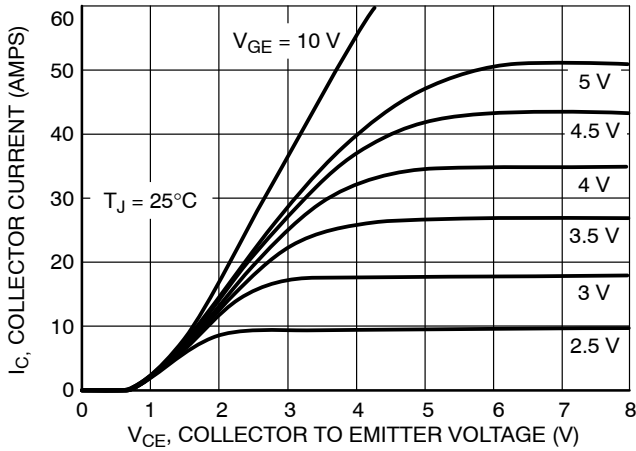


Figure 1. Output Characteristics

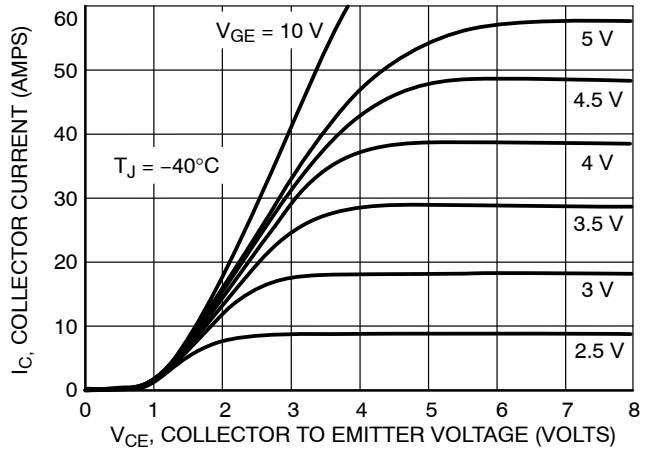


Figure 2. Output Characteristics

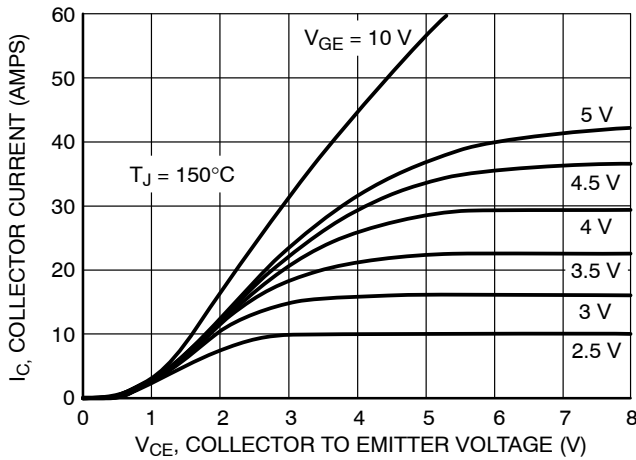


Figure 3. Output Characteristics

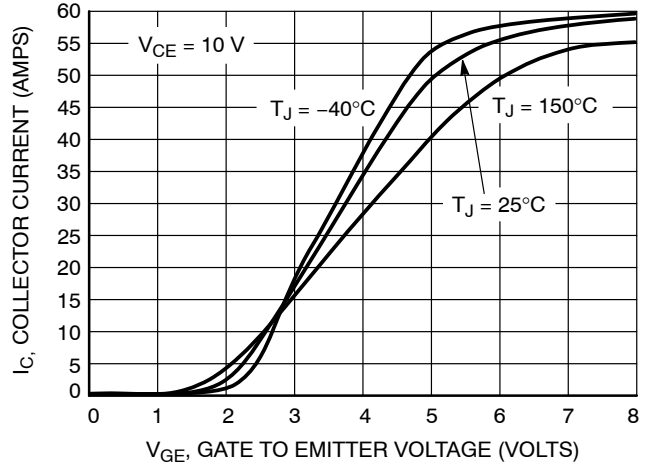


Figure 4. Transfer Characteristics

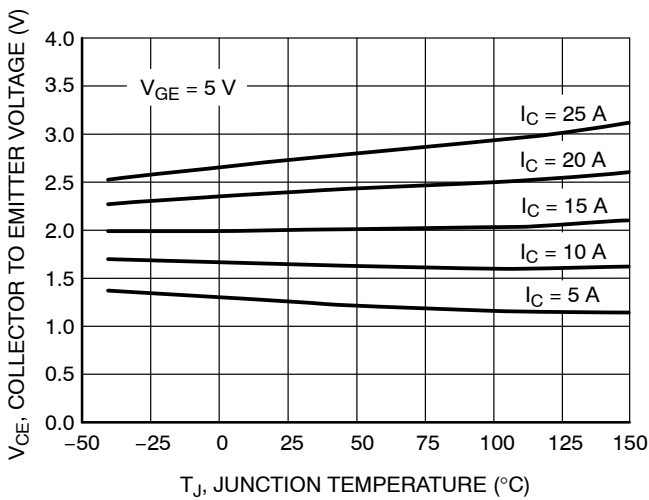


Figure 5. Collector-to-Emitter Saturation Voltage versus Junction Temperature

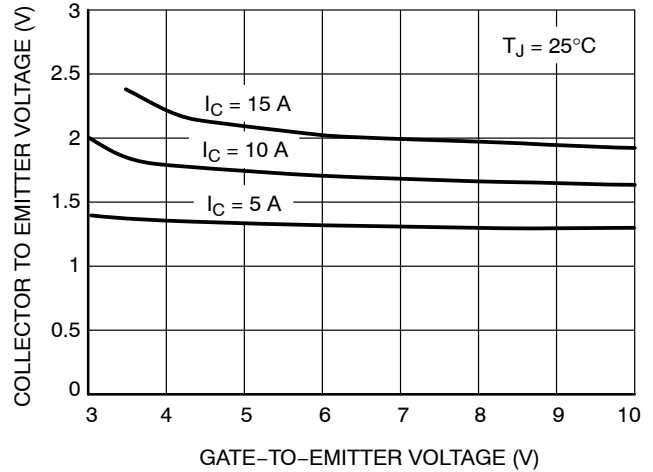


Figure 6. Collector-to-Emitter Voltage versus Gate-to-Emitter Voltage

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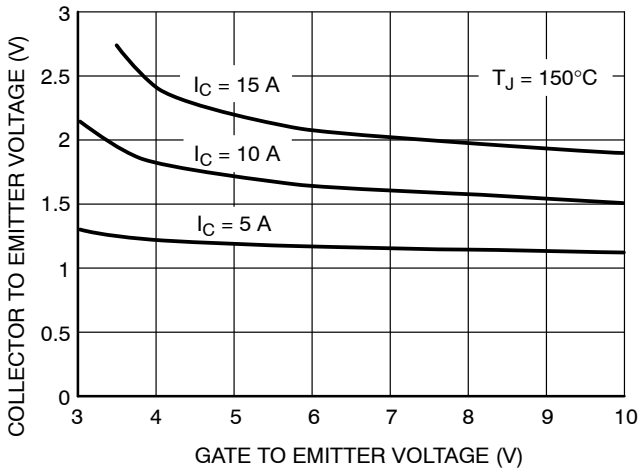


Figure 7. Collector-to-Emitter Voltage versus Gate-to-Emitter Voltage

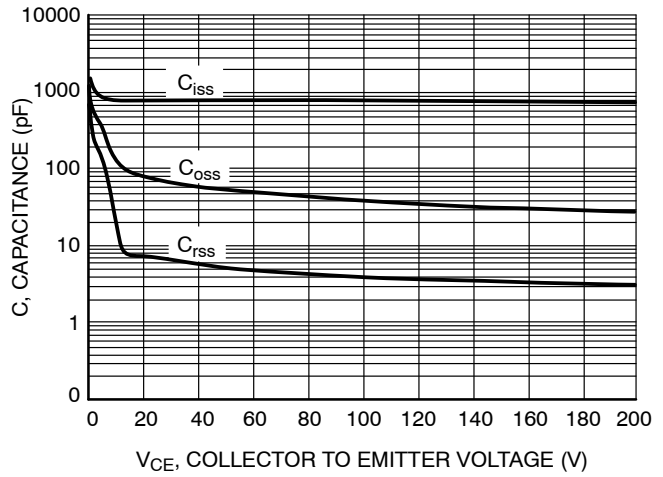


Figure 8. Capacitance Variation

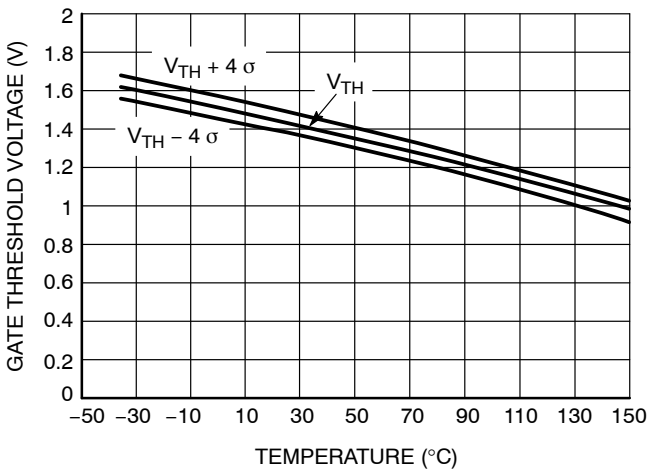


Figure 9. Gate Threshold Voltage versus Temperature

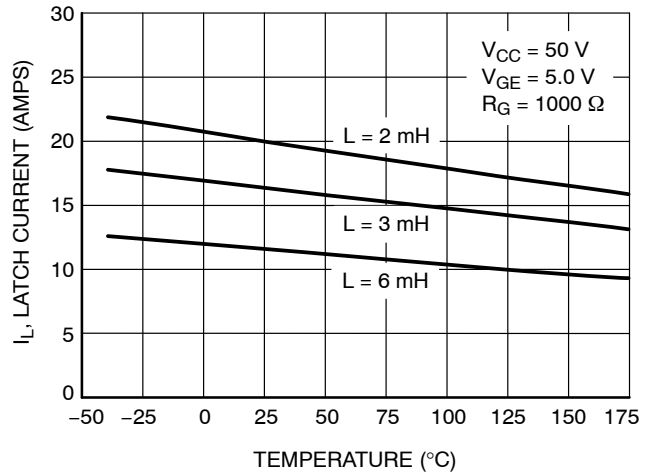


Figure 10. Minimum Open Secondary Latch Current versus Temperature

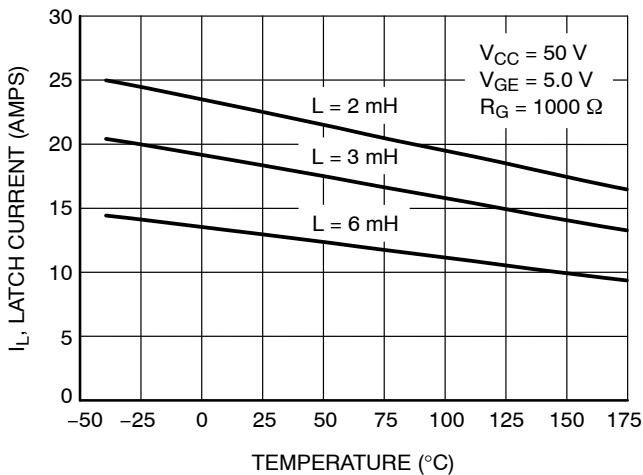


Figure 11. Typical Open Secondary Latch Current versus Temperature

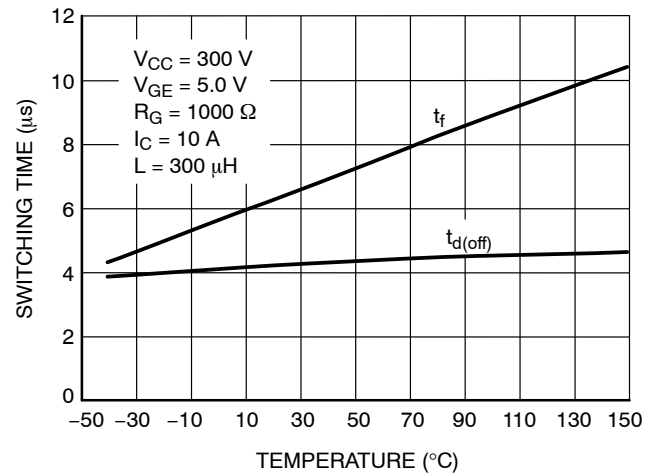


Figure 12. Inductive Switching Fall Time versus Temperature

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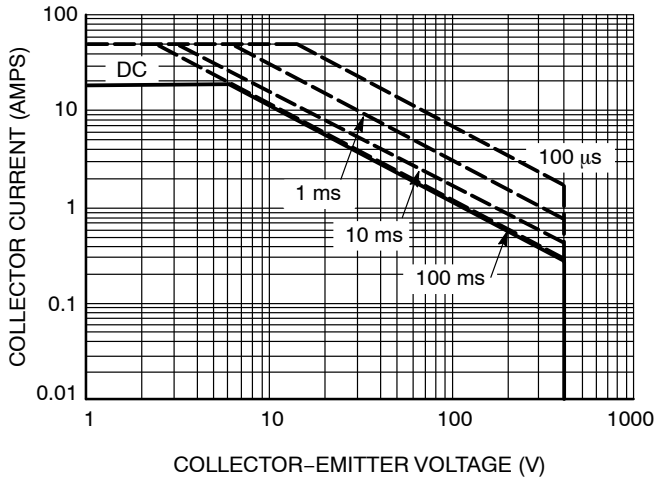


Figure 13. Single Pulse Safe Operating Area (Mounted on an Infinite Heatsink at $T_A = 25^\circ\text{C}$)

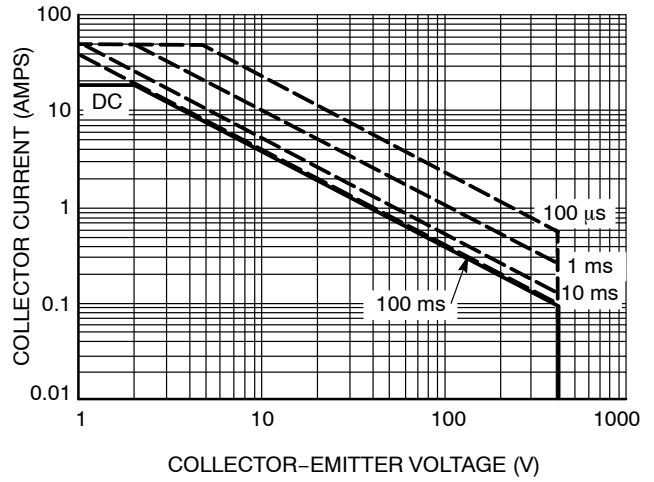


Figure 14. Single Pulse Safe Operating Area (Mounted on an Infinite Heatsink at $T_A = 125^\circ\text{C}$)

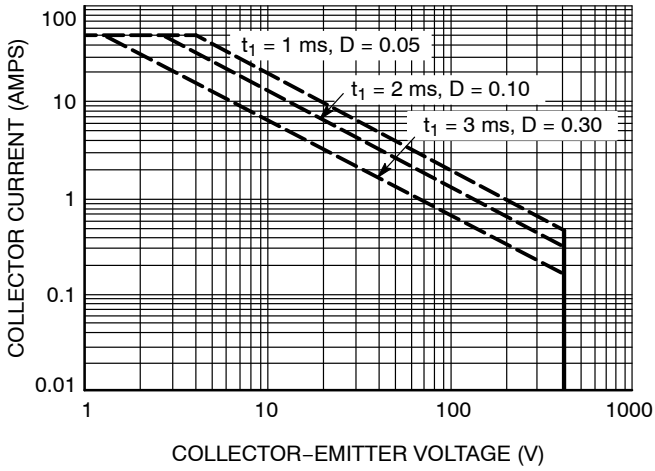


Figure 15. Pulse Train Safe Operating Area (Mounted on an Infinite Heatsink at $T_C = 25^\circ\text{C}$)

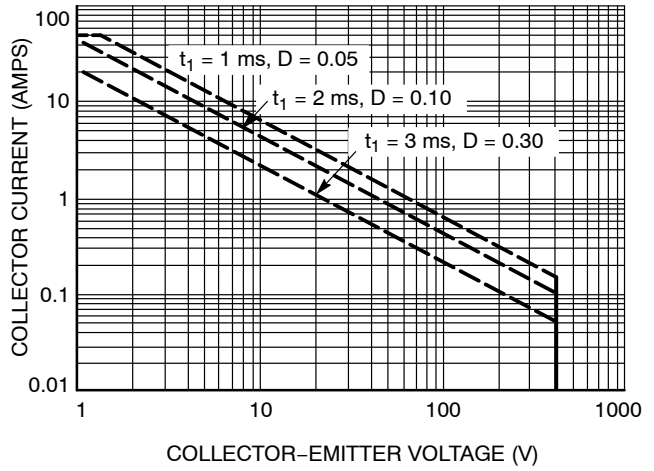


Figure 16. Pulse Train Safe Operating Area (Mounted on an Infinite Heatsink at $T_C = 125^\circ\text{C}$)

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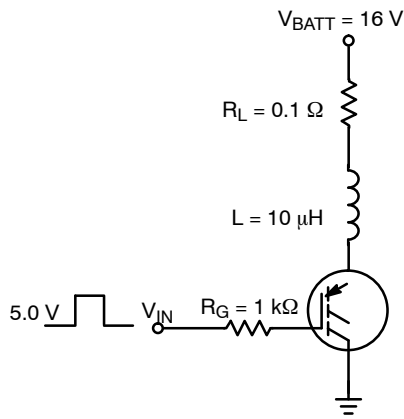


Figure 17. Circuit Configuration for Short Circuit Test #1

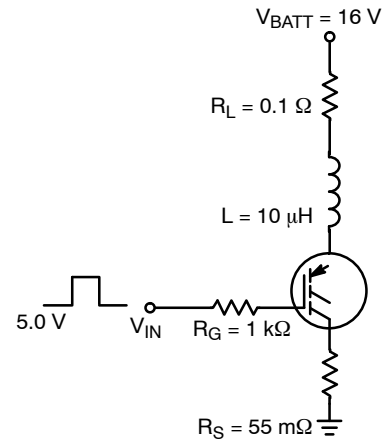


Figure 18. Circuit Configuration for Short Circuit Test #2

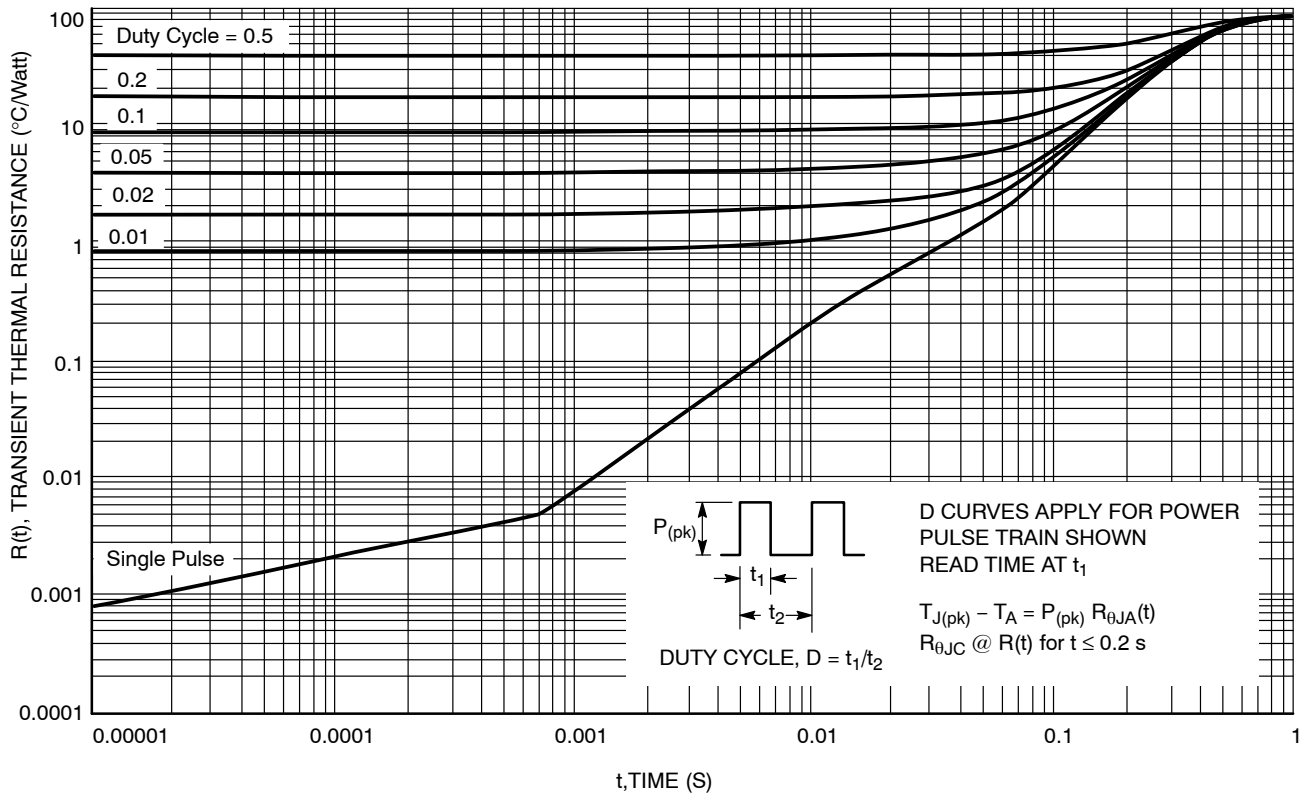
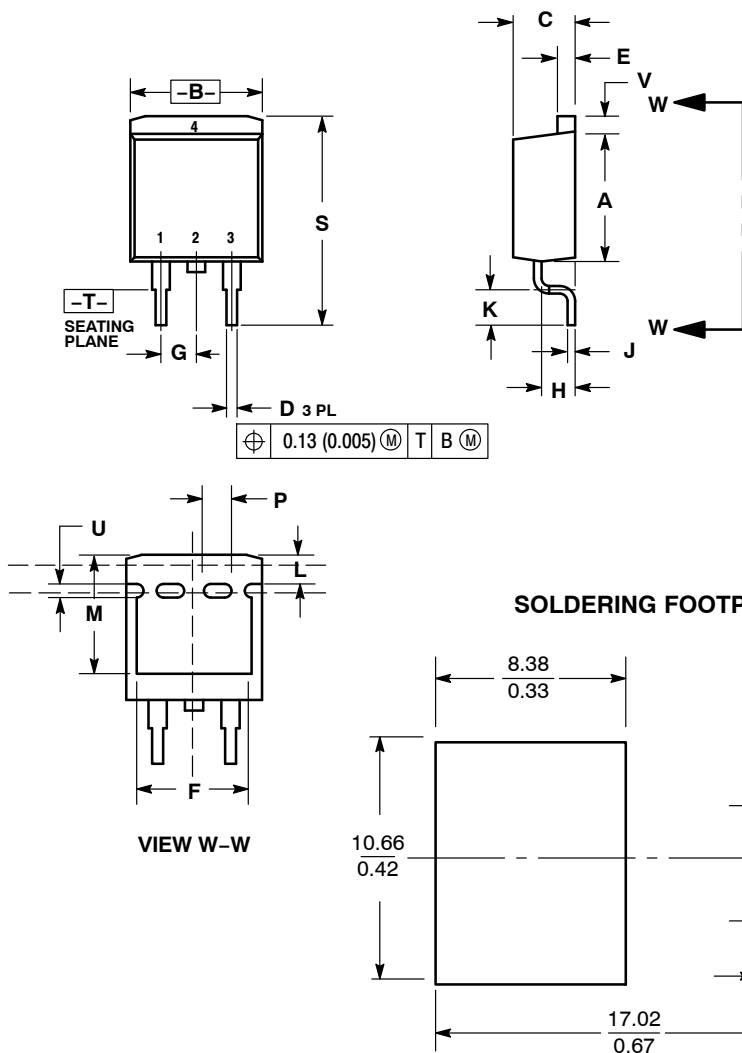


Figure 19. Transient Thermal Resistance (Non-normalized Junction-to-Ambient mounted on minimum pad area)

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PACKAGE DIMENSIONS

D²PAK 3
CASE 418B-04
ISSUE J



NOTES:

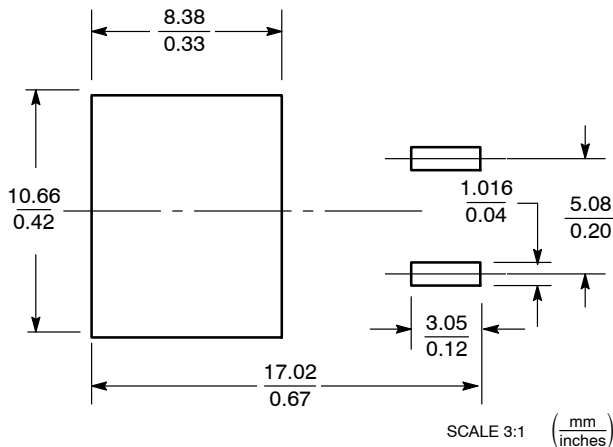
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

STYLE 4:

- PIN 1. GATE
- COLLECTOR
- EMITTER
- COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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